

IFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2852
Examiner: To be assigned

In Re PATENT APPLICATION Of:



Applicants : Mitsuhiro OGIHARA et al.)
Serial No. : 10/734,676)
Filed : December 15, 2003)
For : SEMICONDUCTOR APPARATUS)
HAVING ADHESION LAYER)
AND SEMICONDUCTOR THIN)
FILM)

**REQUEST FOR
CORRECTED
FILING RECEIPT**

Attorney Ref: MAE 304

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Please correct the Official Filing Receipt in the above-captioned matter as follows:
-The Filing Fee Rec'd should be "860" instead of "842".

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Respectfully submitted,

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Date: July 8, 2004

RHB:dt

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- Copy of Official Filing Receipt with Corrections Marked in Red

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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/734,676	12/15/2003	2852	842 <u>860</u>	MAE 304	24	24	1

CONFIRMATION NO. 6298

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FILING RECEIPT



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Title

Semiconductor apparatus having adhesion layer and semiconductor thin film